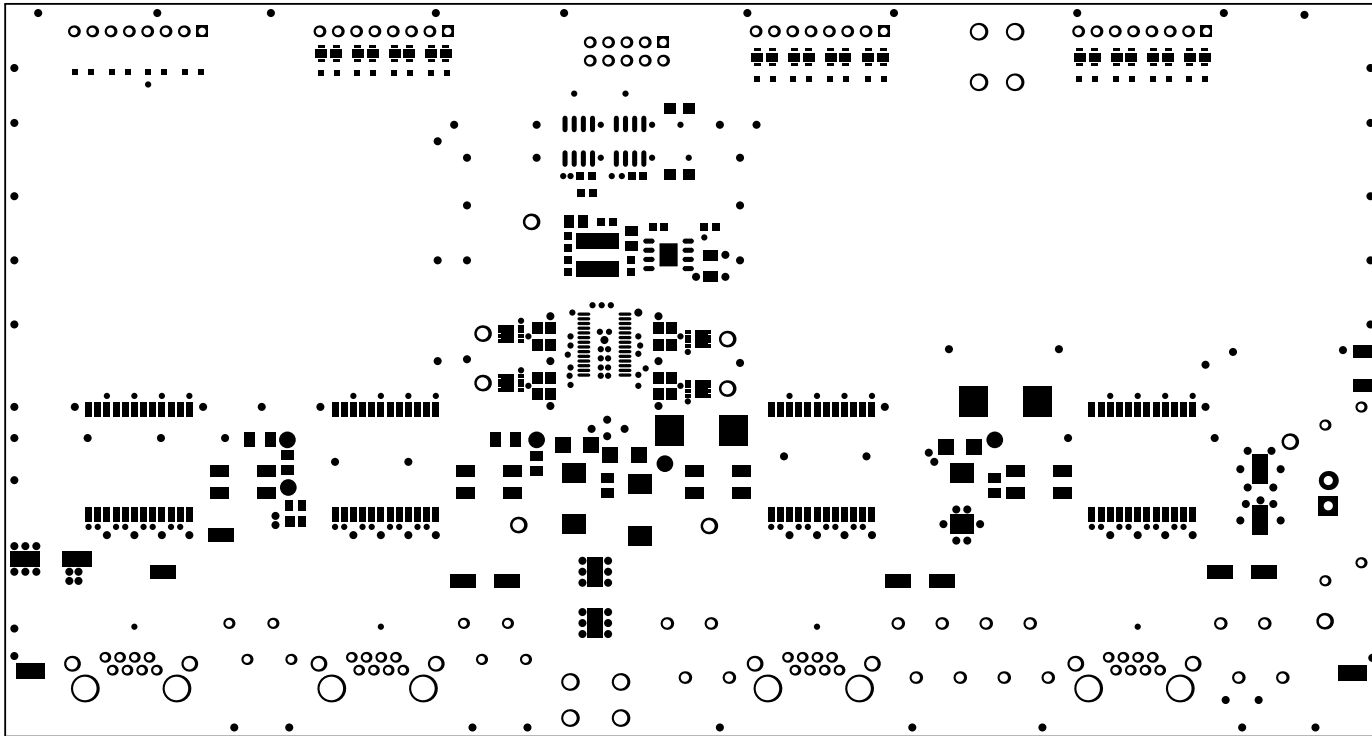
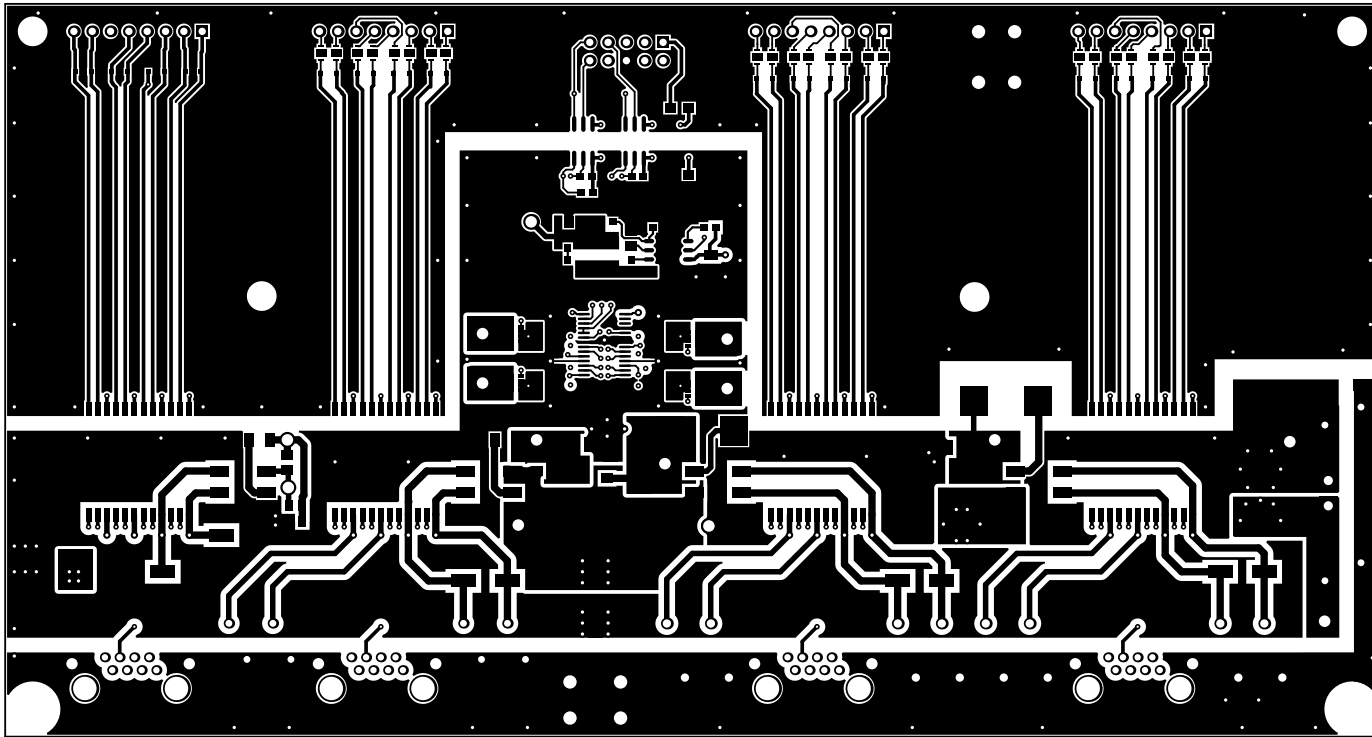


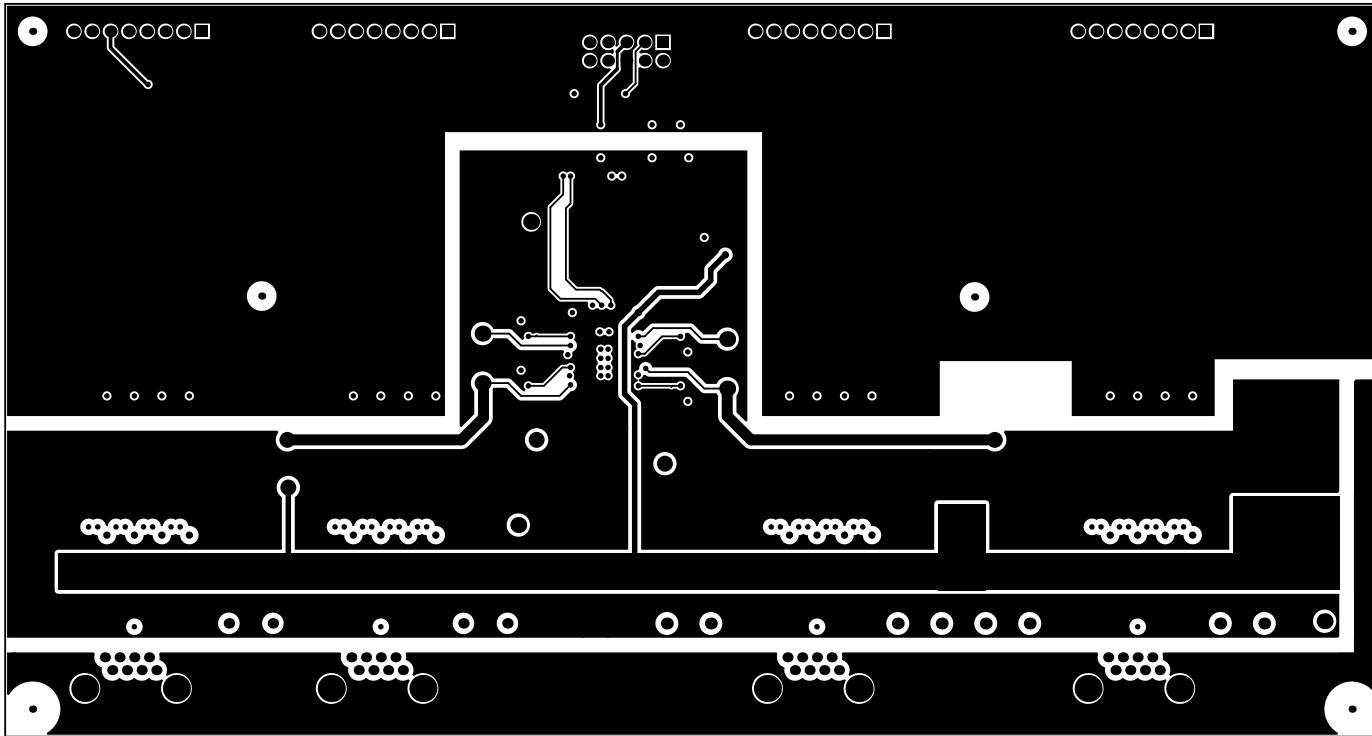
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/21/2017 7:54:31 AM	TEXAS INSTRUMENTS	



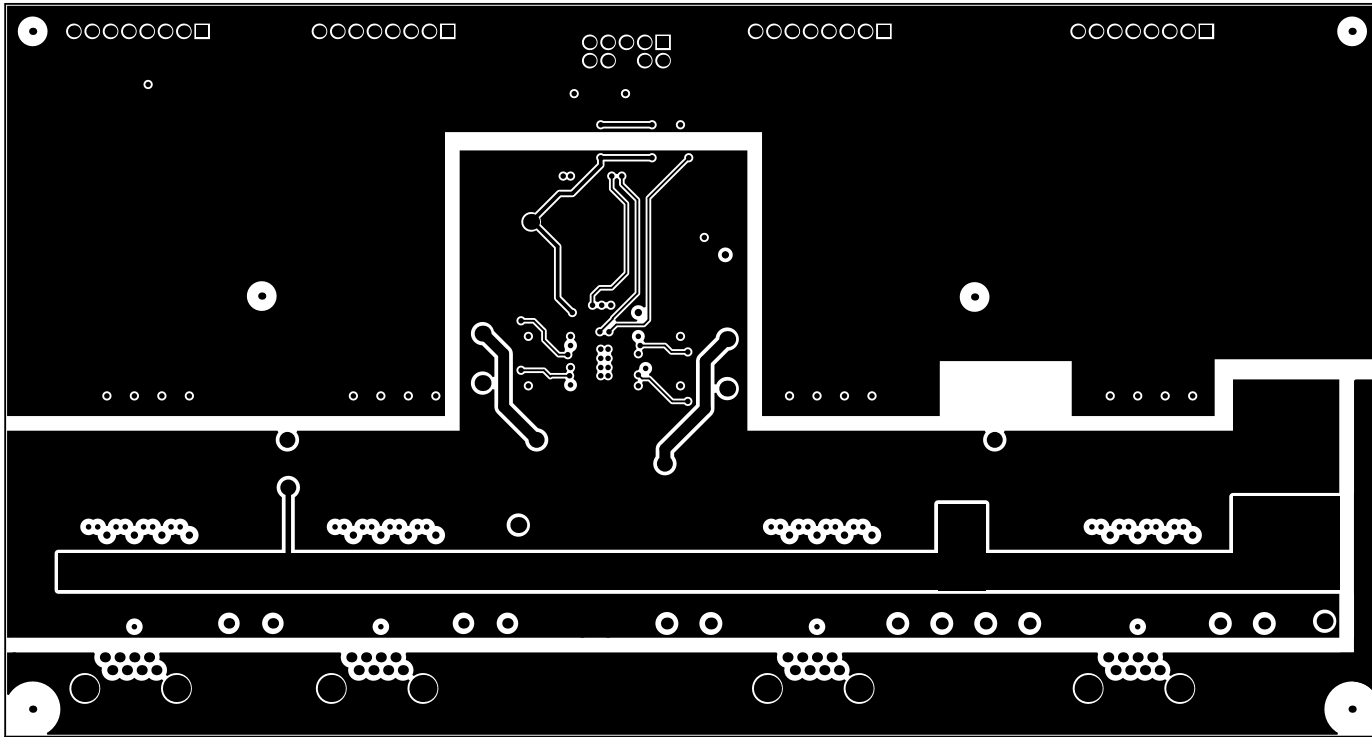
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/21/2017 7:54:33 AM	TEXAS INSTRUMENTS	



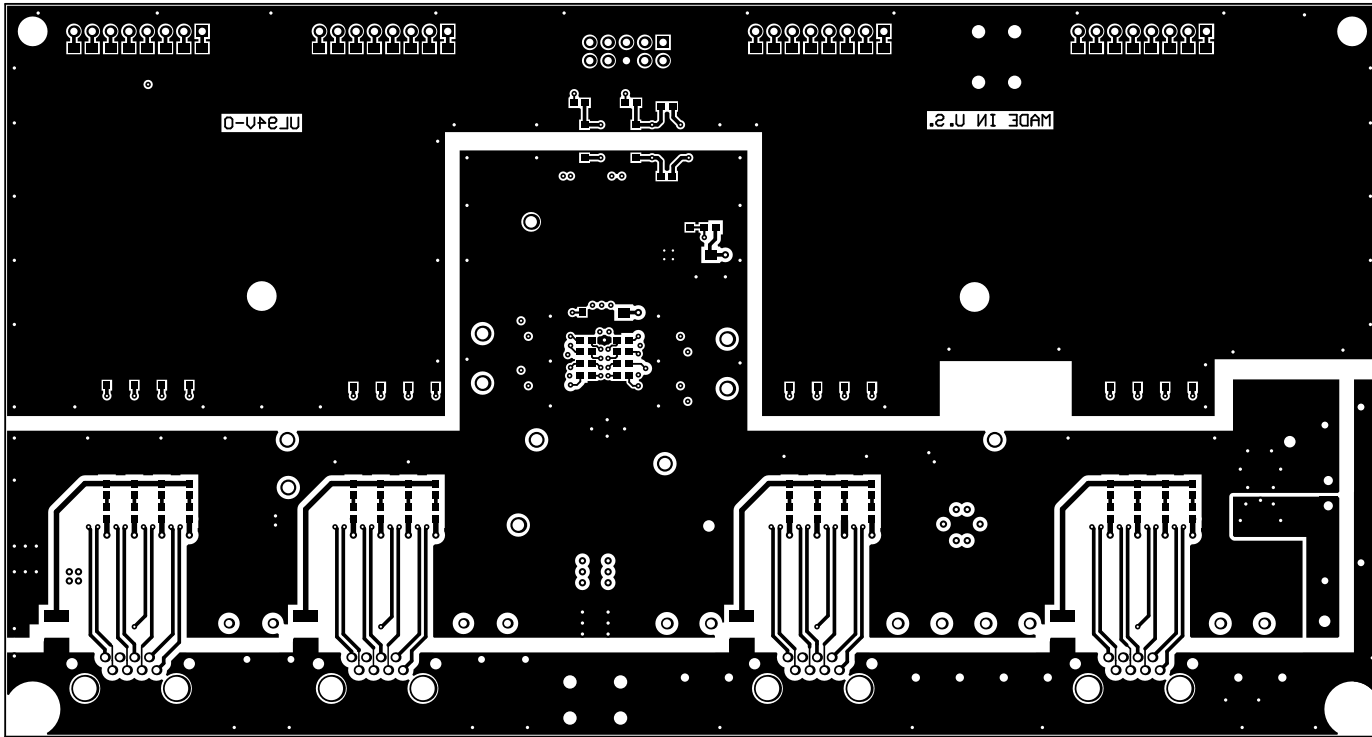
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/21/2017 7:54:33 AM	TEXAS INSTRUMENTS	



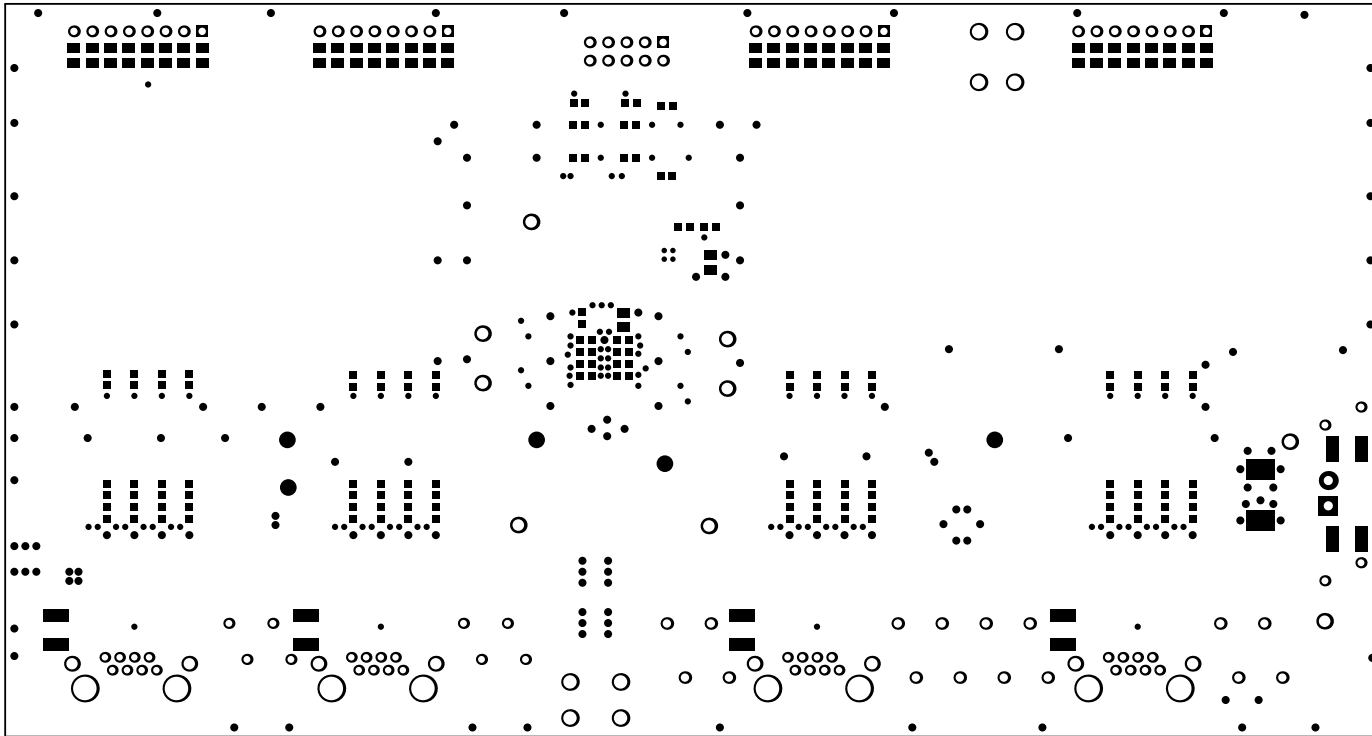
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal 1	GENERATED : 12/21/2017 7:54:34 AM	TEXAS INSTRUMENTS	



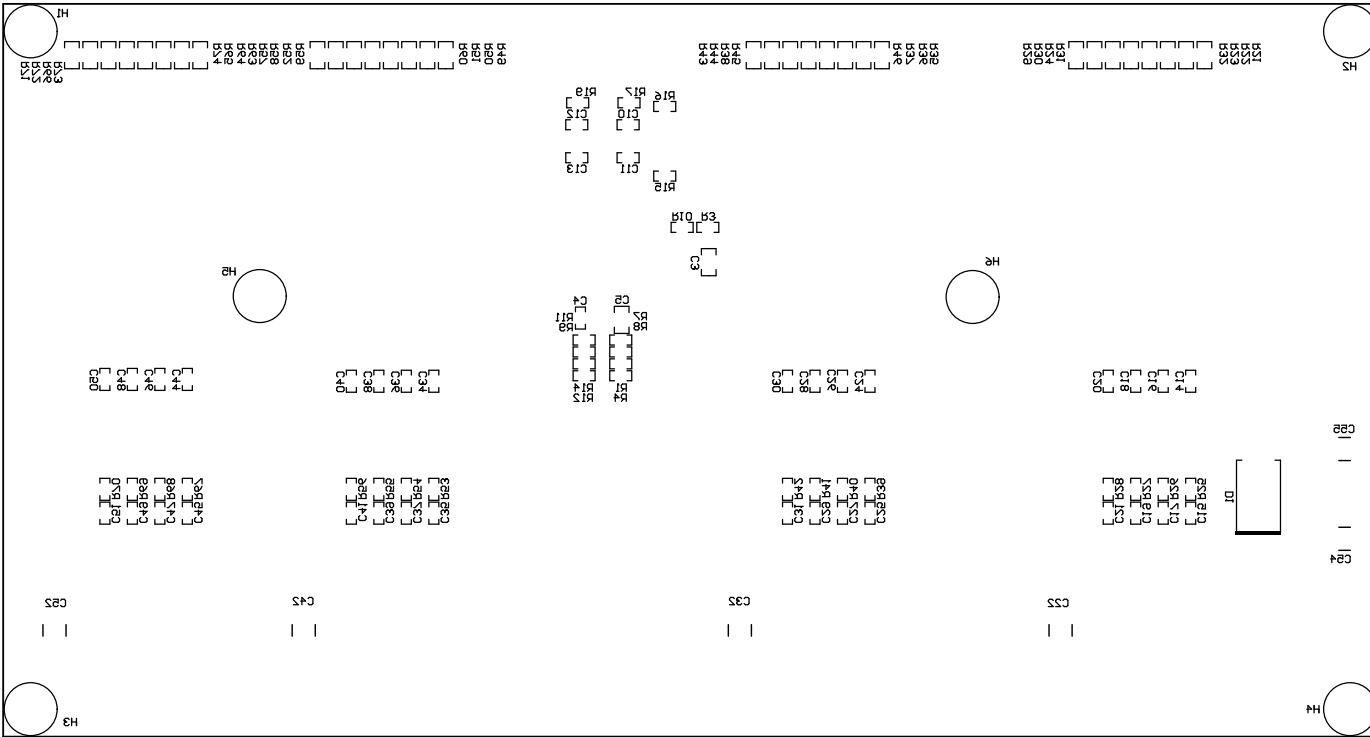
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal 2	GENERATED : 12/21/2017 7:54:34 AM	TEXAS INSTRUMENTS	



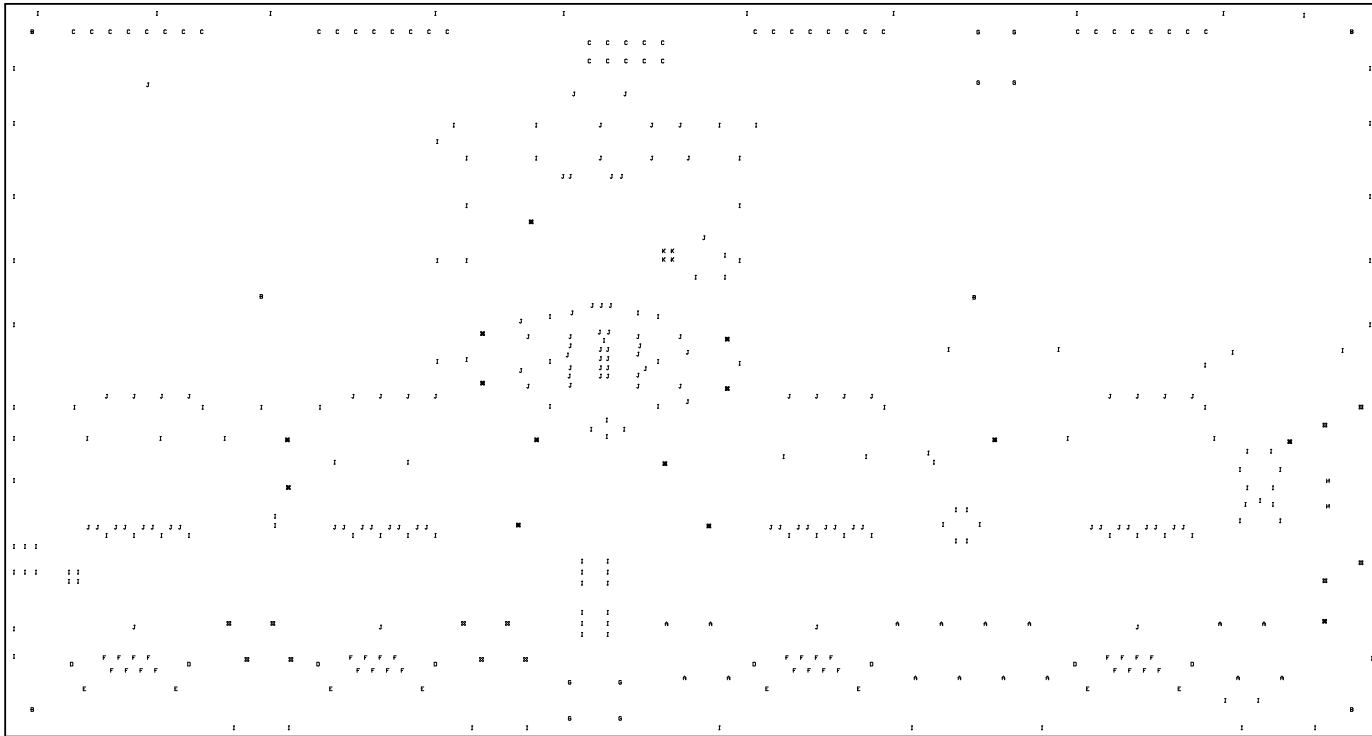
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/21/2017 7:54:35 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/21/2017 7:54:35 AM	TEXAS INSTRUMENTS	



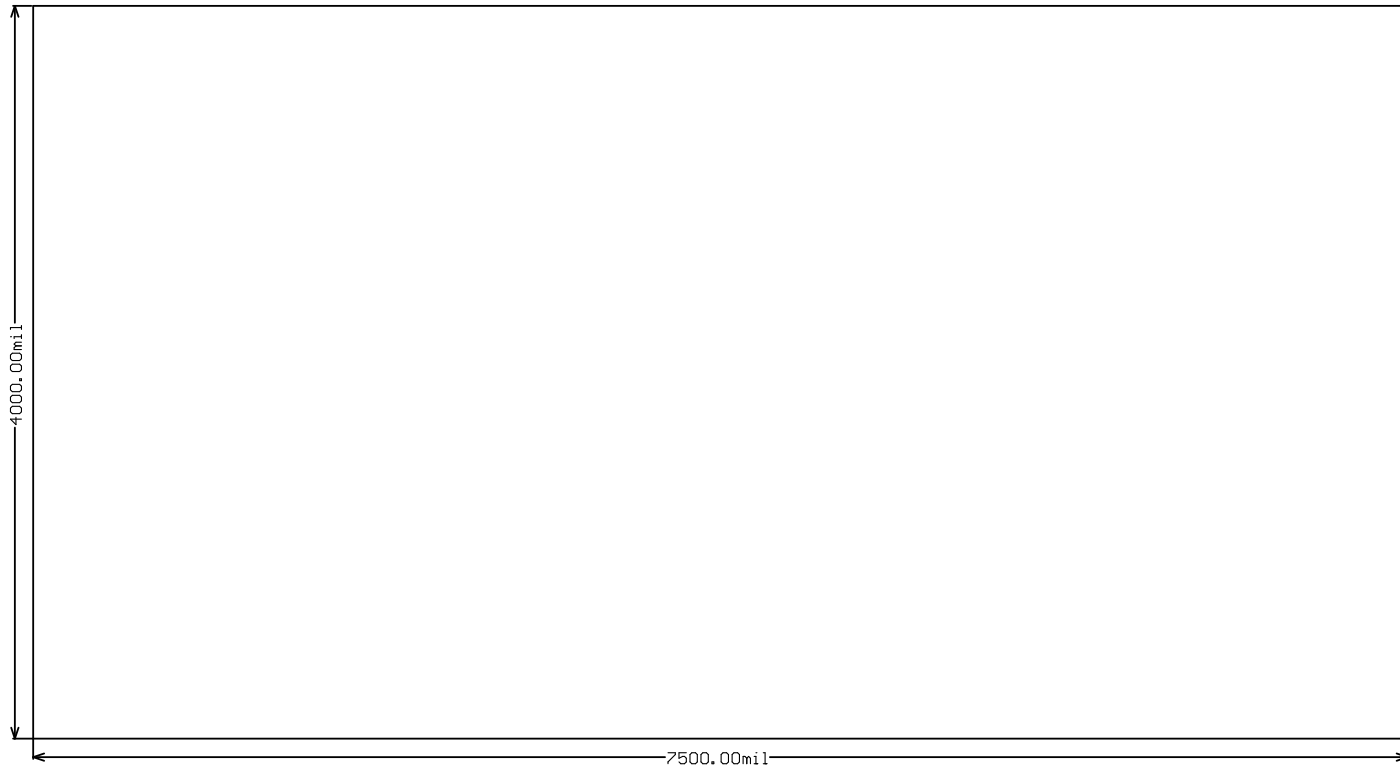
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/21/2017 7:54:35 AM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type
H	2	50.00mil (1.270mm)	PTH	Round
K	4	12.99mil (0.330mm)	PTH	Round
B	6	141.73mil (3.600mm)	NPTH	Round
D	8	61.81mil (1.570mm)	PTH	Round
G	8	72.83mil (1.850mm)	PTH	Round
E	8	128.00mil (3.251mm)	PTH	Round
X	12	37.40mil (0.950mm)	PTH	Round
X	14	63.00mil (1.600mm)	PTH	Round
A	16	45.28mil (1.150mm)	PTH	Round
F	32	35.04mil (0.890mm)	PTH	Round
C	42	40.00mil (1.016mm)	PTH	Round
J	100	12.00mil (0.305mm)	PTH	Round
I	147	18.00mil (0.457mm)	PTH	Round
	399 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/21/2017 7:54:36 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01411	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/21/2017 7:54:38 AM	TEXAS INSTRUMENTS	

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